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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	36-VFTLA Exposed Pad
Supplier Device Package	36-VTLA (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx120f032ct-i-tl

TABLE 4: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN SOIC, SPDIP, SSOP (TOP VIEW)(1,2,3)

PIC32MX210F016B
PIC32MX220F032B
PIC32MX230F064B
PIC32MX230F256B
PIC32MX250F128B
PIC32MX270F256B

Pin #	Full Pin Name	Pin #	Full Pin Name
1	$\overline{\text{MCLR}}$	15	V_{BUS}
2	PGED3/V_{REF}+/CV_{REF}+/AN0/C3INC/RPA0/CTED1/PMD7/RA0	16	TDI/RPB7/CTED3/PMD5/INT0/RB7
3	PGEC3/V_{REF}-/CV_{REF}-/AN1/RPA1/CTED2/PMD6/RA1	17	TCK/RPB8/SCL1/CTED10/PMD4/RB8
4	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	18	TDO/RPB9/SDA1/CTED4/PMD3/RB9
5	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	19	V_{SS}
6	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	20	V_{CAP}
7	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	21	PGED2/RPB10/D+/CTED11/RB10
8	V_{SS}	22	PGEC2/RPB11/D-/RB11
9	OSC1/CLKI/RPA2/RA2	23	V_{USB3V3}
10	OSC2/CLKO/RPA3/PMA0/RA3	24	AN11/RPB13/CTPLS/PMRD/RB13
11	SOSCI/RPB4/RB4	25	CV_{REFOUT}/AN10/C3INB/RPB14/V_{BUSON}/SCK1/CTED5/RB14
12	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	26	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
13	V_{DD}	27	AV_{SS}
14	TMS/RPB5/USBID/RB5	28	AV_{DD}

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

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Referenced Sources

This device data sheet is based on the following individual chapters of the *"PIC32 Family Reference Manual"*. These documents should be considered as the general reference for the operation of a particular module or device feature.

Note: To access the following documents, refer to the *Documentation > Reference Manuals* section of the Microchip PIC32 website: http://www.microchip.com/pic32

- **Section 1. "Introduction"** (DS60001127)
- **Section 2. "CPU"** (DS60001113)
- **Section 3. "Memory Organization"** (DS60001115)
- **Section 5. "Flash Program Memory"** (DS60001121)
- **Section 6. "Oscillator Configuration"** (DS60001112)
- **Section 7. "Resets"** (DS60001118)
- **Section 8. "Interrupt Controller"** (DS60001108)
- **Section 9. "Watchdog Timer and Power-up Timer"** (DS60001114)
- **Section 10. "Power-Saving Features"** (DS60001130)
- **Section 12. "I/O Ports"** (DS60001120)
- **Section 13. "Parallel Master Port (PMP)"** (DS60001128)
- **Section 14. "Timers"** (DS60001105)
- **Section 15. "Input Capture"** (DS60001122)
- **Section 16. "Output Compare"** (DS60001111)
- **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104)
- **Section 19. "Comparator"** (DS60001110)
- **Section 20. "Comparator Voltage Reference (CV_{REF})"** (DS60001109)
- **Section 21. "Universal Asynchronous Receiver Transmitter (UART)"** (DS60001107)
- **Section 23. "Serial Peripheral Interface (SPI)"** (DS60001106)
- **Section 24. "Inter-Integrated Circuit (I^2C)"** (DS60001116)
- **Section 27. "USB On-The-Go (OTG)"** (DS60001126)
- **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS60001125)
- **Section 31. "Direct Memory Access (DMA) Controller"** (DS60001117)
- **Section 32. "Configuration"** (DS60001124)
- **Section 33. "Programming and Diagnostics"** (DS60001129)
- **Section 37. "Charge Time Measurement Unit (CTMU)"** (DS60001167)

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
OC1	PPS	PPS	PPS	PPS	O	—	Output Compare Output 1
OC2	PPS	PPS	PPS	PPS	O	—	Output Compare Output 2
OC3	PPS	PPS	PPS	PPS	O	—	Output Compare Output 3
OC4	PPS	PPS	PPS	PPS	O	—	Output Compare Output 4
OC5	PPS	PPS	PPS	PPS	O	—	Output Compare Output 5
OCFA	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault B Input
INT0	13	16	17	43	I	ST	External Interrupt 0
INT1	PPS	PPS	PPS	PPS	I	ST	External Interrupt 1
INT2	PPS	PPS	PPS	PPS	I	ST	External Interrupt 2
INT3	PPS	PPS	PPS	PPS	I	ST	External Interrupt 3
INT4	PPS	PPS	PPS	PPS	I	ST	External Interrupt 4
RA0	27	2	33	19	I/O	ST	PORTA is a bidirectional I/O port
RA1	28	3	34	20	I/O	ST	
RA2	6	9	7	30	I/O	ST	
RA3	7	10	8	31	I/O	ST	
RA4	9	12	10	34	I/O	ST	
RA7	—	—	—	13	I/O	ST	
RA8	—	—	—	32	I/O	ST	
RA9	—	—	—	35	I/O	ST	
RA10	—	—	—	12	I/O	ST	
RB0	1	4	35	21	I/O	ST	PORTB is a bidirectional I/O port
RB1	2	5	36	22	I/O	ST	
RB2	3	6	1	23	I/O	ST	
RB3	4	7	2	24	I/O	ST	
RB4	8	11	9	33	I/O	ST	
RB5	11	14	15	41	I/O	ST	
RB6	12(2)	15(2)	16(2)	42(2)	I/O	ST	
RB7	13	16	17	43	I/O	ST	
RB8	14	17	18	44	I/O	ST	
RB9	15	18	19	1	I/O	ST	
RB10	18	21	24	8	I/O	ST	
RB11	19	22	25	9	I/O	ST	
RB12	20(2)	23(2)	26(2)	10(2)	I/O	ST	
RB13	21	24	27	11	I/O	ST	
RB14	22	25	28	14	I/O	ST	
RB15	23	26	29	15	I/O	ST	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
SDA1	15	18	19	1	I/O	ST	Synchronous serial data input/output for I2C1
SCL2	4	7	2	24	I/O	ST	Synchronous serial clock input/output for I2C2
SDA2	3	6	1	23	I/O	ST	Synchronous serial data input/output for I2C2
TMS	19[2] 11[3]	22[2] 14[3]	25[2] 15[3]	12	I	ST	JTAG Test mode select pin
TCK	14	17	18	13	I	ST	JTAG test clock input pin
TDI	13	16	17	35	O	—	JTAG test data input pin
TDO	15	18	19	32	O	—	JTAG test data output pin
RTCC	4	7	2	24	O	ST	Real-Time Clock alarm output
CVREF-	28	3	34	20	I	Analog	Comparator Voltage Reference (low)
CVREF+	27	2	33	19	I	Analog	Comparator Voltage Reference (high)
CVREFOUT	22	25	28	14	O	Analog	Comparator Voltage Reference output
C1INA	4	7	2	24	I	Analog	Comparator Inputs
C1INB	3	6	1	23	I	Analog	
C1INC	2	5	36	22	I	Analog	
C1IND	1	4	35	21	I	Analog	
C2INA	2	5	36	22	I	Analog	
C2INB	1	4	35	21	I	Analog	
C2INC	4	7	2	24	I	Analog	
C2IND	3	6	1	23	I	Analog	
C3INA	23	26	29	15	I	Analog	
C3INB	22	25	28	14	I	Analog	
C3INC	27	2	33	19	I	Analog	
C3IND	1	4	35	21	I	Analog	
C1OUT	PPS	PPS	PPS	PPS	O	—	Comparator Outputs
C2OUT	PPS	PPS	PPS	PPS	O	—	
C3OUT	PPS	PPS	PPS	PPS	O	—	

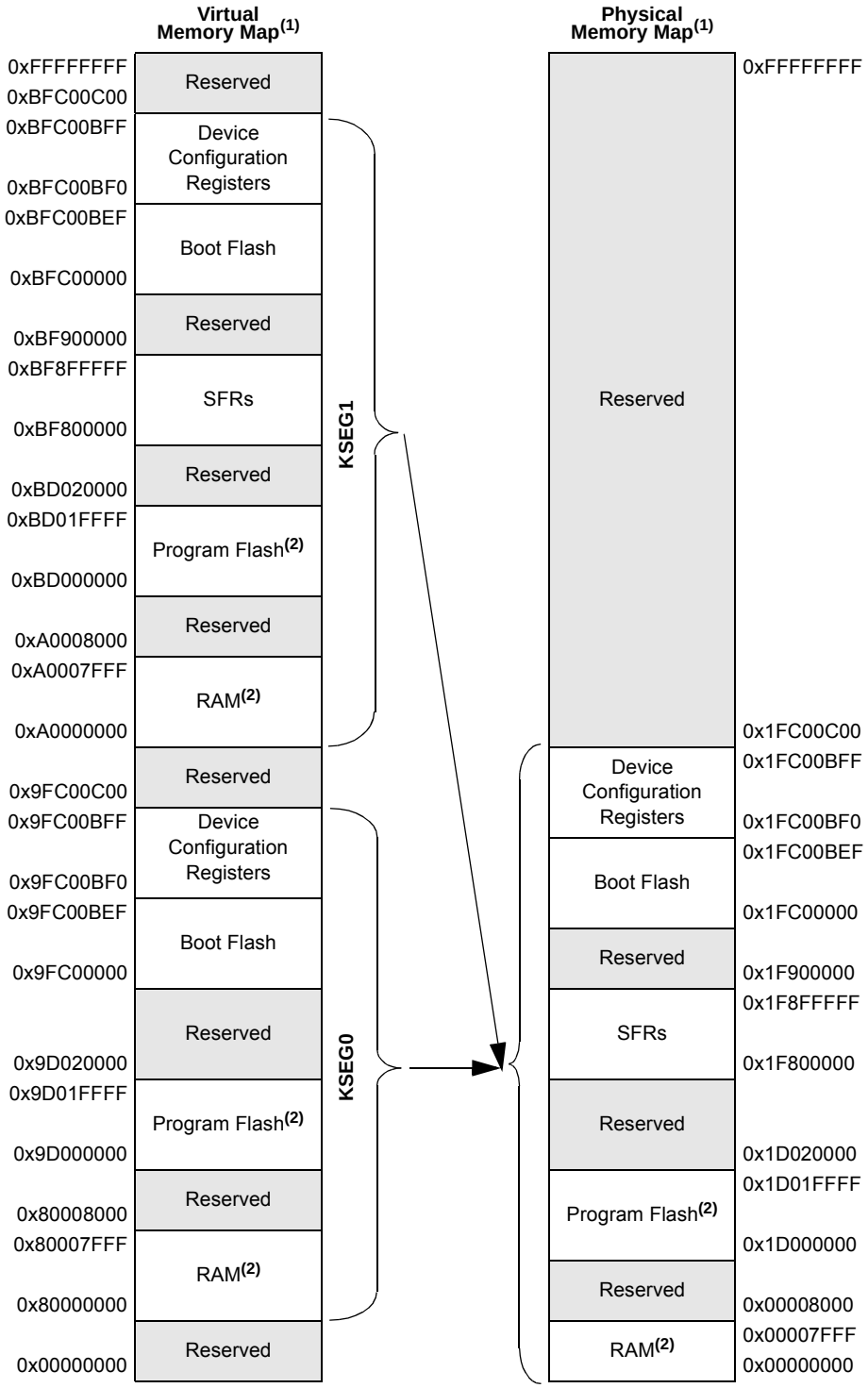
Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

FIGURE 4-4: MEMORY MAP ON RESET FOR PIC32MX150/250 DEVICES (32 KB RAM, 128 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

8.1 Oscillator Control Regiters

TABLE 8-1: OSCILLATOR CONTROL REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F000	OSCCON	31:16	—	—	PLLODIV<2:0>			FRCDIV<2:0>			—	SOSCRDY	PBDIVRDY	PBDIV<1:0>		PLLMULT<2:0>			x1xx(2)
		15:0	—	COSC<2:0>			—	NOSC<2:0>			CLKLOCK	ULOCK(3)	SLOCK	SLPEN	CF	UFRCEN(3)	SOSCEN	OSWEN	xxxx(2)
F010	OSCTUN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TUN<5:0>						0000
F020	REFOCON	31:16	—	RODIV<14:0>															0000
		15:0	ON	—	SIDL	OE	RSLP	—	DIVSWEN	ACTIVE	—	—	—	—	ROSEL<3:0>				0000
F030	REFOTRIM	31:16	ROTRIM<8:0>									—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: Reset values are dependent on the DEVCFGx Configuration bits and the type of reset.

3: This bit is only available on PIC32MX2XX devices.

REGISTER 10-1: U1OTGIR: USB OTG INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	U-0	R/WC-0, HS
	IDIF	T1MSECIF	LSTATEIF	ACTVIF	SESVDIF	SESENDIF	—	VBUSVDIF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **IDIF:** ID State Change Indicator bit
- 1 = A change in the ID state was detected
- 0 = No change in the ID state was detected

bit 6 **T1MSECIF:** 1 Millisecond Timer bit
- 1 = 1 millisecond timer has expired
- 0 = 1 millisecond timer has not expired

bit 5 **LSTATEIF:** Line State Stable Indicator bit
- 1 = USB line state has been stable for 1 ms, but different from last time
- 0 = USB line state has not been stable for 1 ms

bit 4 **ACTVIF:** Bus Activity Indicator bit
- 1 = Activity on the D+, D-, ID or VBUS pins has caused the device to wake-up
- 0 = Activity has not been detected

bit 3 **SESVDIF:** Session Valid Change Indicator bit
- 1 = VBUS voltage has dropped below the session end level
- 0 = VBUS voltage has not dropped below the session end level

bit 2 **SESENDIF:** B-Device VBUS Change Indicator bit
- 1 = A change on the session end input was detected
- 0 = No change on the session end input was detected

bit 1 **Unimplemented:** Read as '0'

bit 0 **VBUSVDIF:** A-Device VBUS Change Indicator bit
- 1 = A change on the session valid input was detected
- 0 = No change on the session valid input was detected

REGISTER 10-18: U1BDTP2: USB BUFFER DESCRIPTOR TABLE PAGE 2 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRH<23:16>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRH<23:16>:** Buffer Descriptor Table Base Address bits

This 8-bit value provides address bits 23 through 16 of the Buffer Descriptor Table base address, which defines the starting location of the Buffer Descriptor Table in system memory.

The 32-bit Buffer Descriptor Table base address is 512-byte aligned.

REGISTER 10-19: U1BDTP3: USB BUFFER DESCRIPTOR TABLE PAGE 3 REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BDTPTRU<31:24>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **BDTPTRU<31:24>:** Buffer Descriptor Table Base Address bits

This 8-bit value provides address bits 31 through 24 of the Buffer Descriptor Table base address, defines the starting location of the Buffer Descriptor Table in system memory.

The 32-bit Buffer Descriptor Table base address is 512-byte aligned.

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FA54	U1CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U1CTSR<3:0>				0000
FA58	U2RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2RXR<3:0>				0000
FA5C	U2CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2CTSR<3:0>				0000
FA84	SDI1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI1R<3:0>				0000
FA88	SS1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS1R<3:0>				0000
FA90	SDI2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI2R<3:0>				0000
FA94	SS2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS2R<3:0>				0000
FAB8	REFCLKIR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKIR<3:0>				0000

REGISTER 17-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 17 **SPIFE:** Frame Sync Pulse Edge Select bit (Framed SPI mode only)
1 = Frame synchronization pulse coincides with the first bit clock
0 = Frame synchronization pulse precedes the first bit clock

bit 16 **ENHBUF:** Enhanced Buffer Enable bit(2)
1 = Enhanced Buffer mode is enabled
0 = Enhanced Buffer mode is disabled

bit 15 **ON:** SPI Peripheral On bit(1)
1 = SPI Peripheral is enabled
0 = SPI Peripheral is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode

bit 12 **DISSDO:** Disable SDOx pin bit
1 = SDOx pin is not used by the module. Pin is controlled by associated PORT register
0 = SDOx pin is controlled by the module

bit 11-10 **MODE<32,16>:** 32/16-Bit Communication Select bits

When AUDEN = 1:

MODE32	MODE16	Communication
1	1	24-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
1	0	32-bit Data, 32-bit FIFO, 32-bit Channel/64-bit Frame
0	1	16-bit Data, 16-bit FIFO, 32-bit Channel/64-bit Frame
0	0	16-bit Data, 16-bit FIFO, 16-bit Channel/32-bit Frame

When AUDEN = 0:

MODE32	MODE16	Communication
1	x	32-bit
0	1	16-bit
0	0	8-bit

bit 9 **SMP:** SPI Data Input Sample Phase bit
Master mode (MSTEN = 1):
1 = Input data sampled at end of data output time
0 = Input data sampled at middle of data output time
Slave mode (MSTEN = 0):
SMP value is ignored when SPI is used in Slave mode. The module always uses SMP = 0.
To write a '1' to this bit, the MSTEN value = 1 must first be written.

bit 8 **CKE:** SPI Clock Edge Select bit(3)
1 = Serial output data changes on transition from active clock state to Idle clock state (see the CKP bit)
0 = Serial output data changes on transition from Idle clock state to active clock state (see the CKP bit)

bit 7 **SSEN:** Slave Select Enable (Slave mode) bit
1 = $\overline{SSx}$ pin used for Slave mode
0 = $\overline{SSx}$ pin not used for Slave mode, pin controlled by port function.

bit 6 **CKP:** Clock Polarity Select bit(4)
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

Note 1: When using the 1:1 PBCLK divisor, the user's software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

NOTES:

REGISTER 20-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	CS1(1) / ADDR14(2)	—	—	—	ADDR<10:8>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	ADDR<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-15 **Unimplemented:** Read as '0'

bit 14 **CS1:** Chip Select 1 bit(1)
- 1 = Chip Select 1 is active
- 0 = Chip Select 1 is inactive

bit 14 **ADDR<14>:** Destination Address bit 14(2)

bit 13-11 **Unimplemented:** Read as '0'

bit 10-0 **ADDR<10:0>:** Destination Address bits

Note 1: When the CSF<1:0> bits (PMCON<7:6>) = 10.

2: When the CSF<1:0> bits (PMCON<7:6>) = 00 or 01.

REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence

bit 3 **Unimplemented:** Read as '0'

bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set

bit 1 **SAMP:** ADC Sample Enable bit(2)
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.

bit 0 **DONE:** Analog-to-Digital Conversion Status bit(3)
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

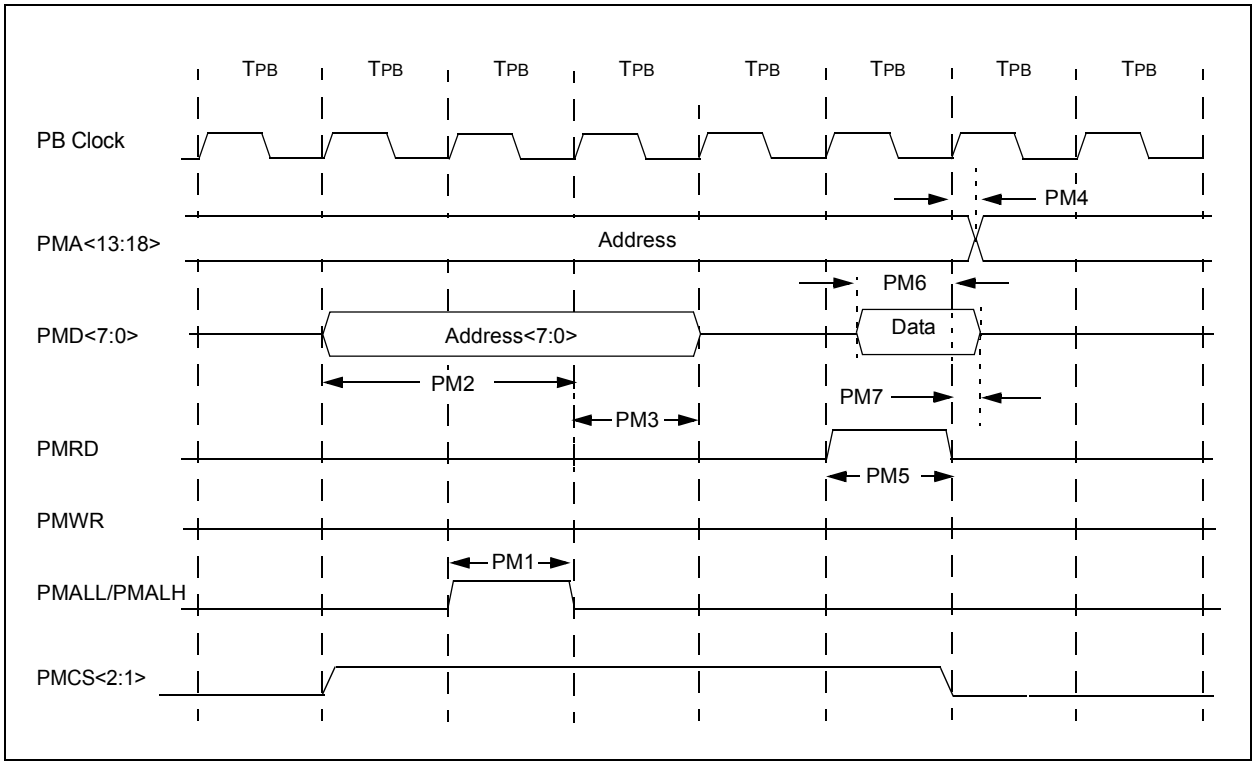
3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

TABLE 30-37: PARALLEL SLAVE PORT REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param.No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
PS1	TdtV2wrH	Data In Valid before $\overline{WR}$ or $\overline{CS}$ Inactive (setup time)	20	—	—	ns	—
PS2	TwrH2dtI	$\overline{WR}$ or $\overline{CS}$ Inactive to Data-In Invalid (hold time)	40	—	—	ns	—
PS3	TrdL2dtV	$\overline{RD}$ and $\overline{CS}$ Active to Data-Out Valid	—	—	60	ns	—
PS4	TrdH2dtI	$\overline{RD}$ Active or $\overline{CS}$ Inactive to Data-Out Invalid	0	—	10	ns	—
PS5	Tcs	$\overline{CS}$ Active Time	TPB + 40	—	—	ns	—
PS6	TWR	$\overline{WR}$ Active Time	TPB + 25	—	—	ns	—
PS7	TRD	$\overline{RD}$ Active Time	TPB + 25	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-21: PARALLEL MASTER PORT READ TIMING DIAGRAM

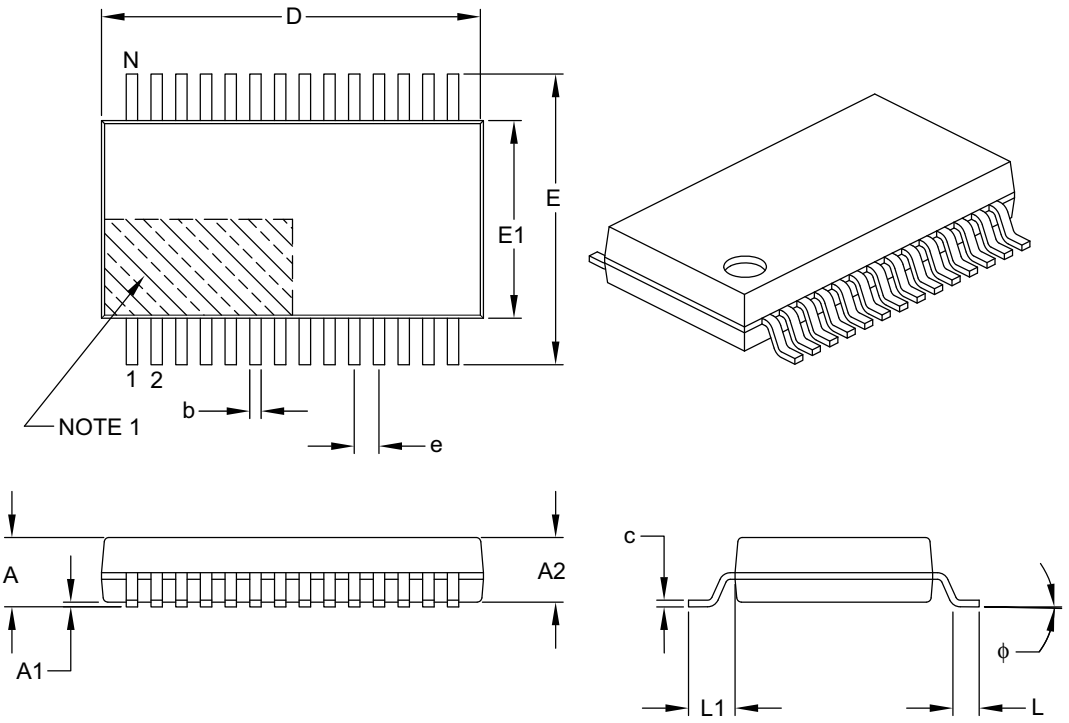


33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		0.65 BSC	
Overall Height	A	–	–	2.00
Molded Package Thickness	A2	1.65	1.75	1.85
Standoff	A1	0.05	–	–
Overall Width	E	7.40	7.80	8.20
Molded Package Width	E1	5.00	5.30	5.60
Overall Length	D	9.90	10.20	10.50
Foot Length	L	0.55	0.75	0.95
Footprint	L1		1.25 REF	
Lead Thickness	c	0.09	–	0.25
Foot Angle	ϕ	0°	4°	8°
Lead Width	b	0.22	–	0.38

Notes:

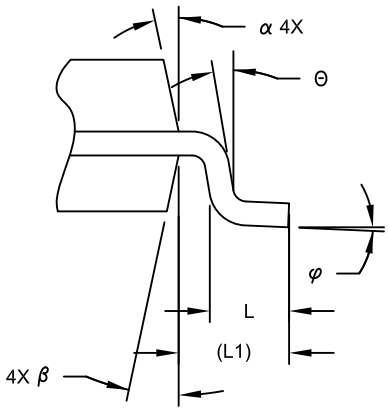
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

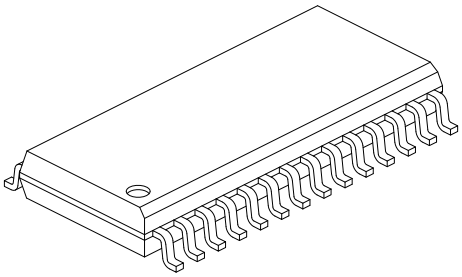
Microchip Technology Drawing C04-073B

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



VIEW C



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		28	
Pitch	e		1.27 BSC	
Overall Height	A	-	-	2.65
Molded Package Thickness	A2	2.05	-	-
Standoff §	A1	0.10	-	0.30
Overall Width	E		10.30 BSC	
Molded Package Width	E1		7.50 BSC	
Overall Length	D		17.90 BSC	
Chamfer (Optional)	h	0.25	-	0.75
Foot Length	L	0.40	-	1.27
Footprint	L1		1.40 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	c	0.18	-	0.33
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic
3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A & B to be determined at Datum H.

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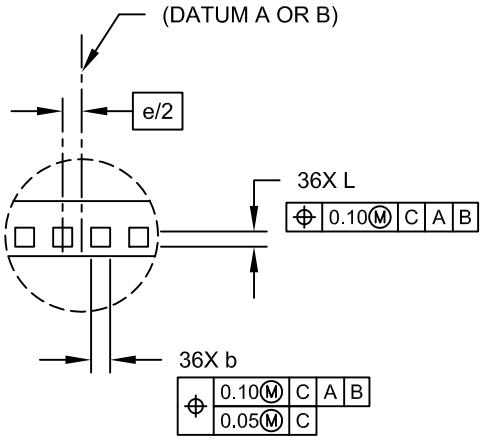
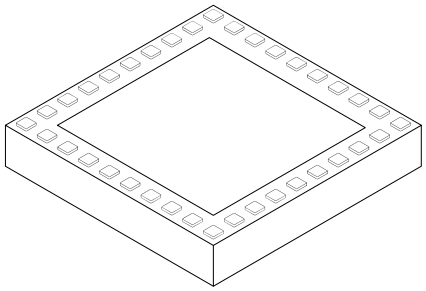
36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section	Update Description
29.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings (removed Voltage on VCORE with respect to VSS). Added the SPDIP specification to the Thermal Packaging Characteristics (see Table 29-2). Updated the Typical values for parameters DC20-DC24 in the Operating Current (IDD) specification (see Table 29-5). Updated the Typical values for parameters DC30a-DC34a in the Idle Current (IIDLE) specification (see Table 29-6). Updated the Typical values for parameters DC40i and DC40n and removed parameter DC40m in the Power-down Current (IPD) specification (see Table 29-7). Removed parameter D320 (VCORE) from the Internal Voltage Regulator Specifications and updated the Comments (see Table 29-13). Updated the Minimum, Typical, and Maximum values for parameter F20b in the Internal FRC Accuracy specification (see Table 29-17). Removed parameter SY01 (TPWRT) and removed all Conditions from Resets Timing (see Table 29-20). Updated all parameters in the CTMU Specifications (see Table 29-39).
31.0 "Packaging Information"	Added the 28-lead SPDIP package diagram information (see **31.1 "Package Marking Information"** and **31.2 "Package Details"**).
"Product Identification System**"**	Added the SPDIP (SP) package definition.

Revision C (November 2011)

All major changes are referenced by their respective section in Table A-2.

TABLE A-2: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog**"**	Revised the source/sink on I/O pins (see **"Input/Output"** on page 1). Added the SPDIP package to the PIC32MX220F032B device in the PIC32MX2XX USB Family Features (see Table 2).
4.0 "Memory Organization"	Removed ANSB6 from the ANSELB register and added the ODCB6, ODCB10, and ODCB11 bits in the PORTB Register Map (see Table 4-20).
29.0 "Electrical Characteristics"	Updated the minimum value for parameter OS50 in the PLL Clock Timing Specifications (see Table 29-16).

Revision J (April 2016)

This revision includes the following major changes as described in Table A-8, as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-8: MAJOR SECTION UPDATES

Section	Update Description
"32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog"	The PIC32MX270FDB device and Note 4 were added to **TABLE 2: "PIC32MX2XX 28/36/44-pin USB Family Features"**.
2.0 "Guidelines for Getting Started with 32-bit MCUs"	**EXAMPLE 2-1: "Crystal Load Capacitor Calculation"** was updated.
30.0 "Electrical Characteristics"	Parameter DO50a (CSOSC) was removed from the Capacitive Loading Requirements on Output Pins AC Characteristics (see Table 30-16).
"Product Identification System"	The device mapping was updated to include type B for Software Targeting.